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# Onsemi

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## MOSFET - Power, N-Channel, SUPERFET<sup>®</sup> III, FRFET<sup>®</sup> 650 V, 36 A, 90 mΩ

# NTMT090N65S3HF

#### Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power systems for miniaturization and higher efficiency.

SUPERFET III FRFET MOSFET's optimized reverse recovery performance of body diode can remove additional components and improve system reliability.

The Power88 package is an ultra-slim surface-mount package (1 mm high) with a low profile and small footprint (8x8 mm<sup>2</sup>). SUPERFET III MOSFET in a Power88 package offers excellent switching performance due to lower parasitic source inductance and separated power and drive sources. Power88 offers Moisture Sensitivity Level 1 (MSL 1).

#### Features

- 700 V @  $T_J = 150^{\circ}C$
- Typ  $R_{DS(on)} = 75 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 66 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 569 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

#### Applications

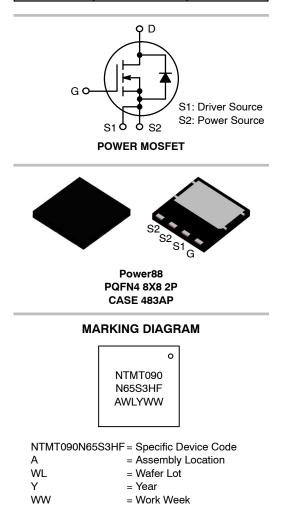
- Telecom / Server Power Supplies
- Industrial Power Supplies
- UPS / Solar
- Lighting / Charger / Adapter



## **ON Semiconductor®**

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V <sub>DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
650 V	90 mΩ @ 10 V	36 A



#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter		Value	Unit				
V <sub>DSS</sub>	Drain to Source Voltage		650	V				
V <sub>GSS</sub>	Gate to Source Voltage	DC	±30	V				
		AC (f > 1 Hz)	±30	V				
Ι <sub>D</sub>	Drain Current	Continuous (T <sub>C</sub> = 25°C)	36	А				
		Continuous (T <sub>C</sub> = 100°C)	22.8					
I <sub>DM</sub>	Drain Current Pulsed (Note 1)	DM Drain Current Pulsed (Note 1)	I <sub>DM</sub> Drain Current Pulsed (Note 1)	Pulsed (Note 1)	Pulsed (Note 1)	90	А	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		440	mJ				
I <sub>AS</sub>	Avalanche Current (Note 2)		4.6	А				
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		2.72	mJ				
dv/dt	MOSFET dv/dt		100	V/ns				
	Peak Diode Recovery dv/dt (Note 3)		50					
PD	Power Dissipation	(T <sub>C</sub> = 25°C)	272	W				
	Derate Above 25°C		2.176	W/°C				
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C				
TL	Maximum Lead Temperature for Soldering, 1	/8″ from Case for 5 s	300	°C				

#### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, Unless otherwise specified)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2.  $I_{AS} = 4.6 \text{ A}, R_G = 25 \Omega \text{ starting } T_J = 25^{\circ}\text{C}$ 3.  $I_{SD} \le 18 \text{ A}, \text{ di/dt} \le 100 \text{ A/}\mu\text{s}, \text{ V}_{DD} \le 400 \text{ V}, \text{ starting } T_J = 25^{\circ}\text{C}$ 

#### THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\thetaJC}$	Thermal Resistance, Junction to Case, Max.	0.46	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max. (Note 4)	45	

4. Device on 1 in<sup>2</sup> pad 2 oz copper pad on 1.5 x 1.5 in. board of FR-4 material.

#### **ORDERING INFORMATION**

Part Number	Top Marking	Package	Reel Size	Tape Width	Shipping <sup>†</sup>
NTMT090N65S3HF	NTMT090N65S3HF	Power88	13"	13.3 mm	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
FF CHARA	ACTERISTICS					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$V_{GS}$ = 0 V, $I_D$ = 1 mA, $T_J$ = 25°C	650	-	-	V
		$V_{GS}$ = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 150°C	700	-	-	V
$\Delta BV_{DSS}$ / $\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	$I_D = 10$ mA, referenced to 25°C	-	0.63	_	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 650 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	10	μA
		$V_{DS}$ = 520 V, $T_{C}$ = 125 °C	-	14		
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 30$ V, $V_{DS} = 0$ V	-	-	±100	nA
N CHARA	CTERISTICS		-	-	•	<u>P</u>

V <sub>GS(th</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 0.86 \text{ mA}$	3.0	-	5.0	V
R <sub>DS(or</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 18 A	-	75	90	mΩ
9fs	Forward Transconductance	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 18 \text{ A}$	-	22	-	S

#### DYNAMIC CHARACTERISTICS

C <sub>iss</sub>	Input Capacitance	$V_{DS}$ = 400 V, $V_{GS}$ = 0 V, f = 1 MHz	-	2930	-	pF
C <sub>oss</sub>	Output Capacitance		-	61	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V	-	569	-	pF
C <sub>oss(er.)</sub>	Energy Related Output Capacitance	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V	-	110	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V	$V_{DS} = 400 \text{ V}, \text{ I}_{D} = 18 \text{ A}, \text{ V}_{GS} = 10 \text{ V}$	-	66	-	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	(Note 5)	-	21	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		-	25	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	1.8	-	Ω

SWITCHING CHARACTERISTICS

t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD}$ = 400 V, $I_{D}$ = 18 A, $V_{GS}$ = 10 V, $R_{GEN}$ = 4.7 $\Omega$	_	31	-	ns
t <sub>r</sub>	Rise Time	(Note 5)	-	19	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	75	-	ns
t <sub>f</sub>	Fall Time		-	3.1	-	ns

SOURCE-DRAIN DIODE CHARACTERISTICS

۱ <sub>S</sub>	Maximum Continuous Source to Drain Diode Forward Current		-	-	36	А
I <sub>SM</sub>	Maximum Pulsed Source to Drain Diode Forward Current		-	-	90	А
V <sub>SD</sub>	Source to Drain Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 18 A	-	-	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 V, I_{SD} = 18 A,$	-	95	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	di <sub>F</sub> /dt = 100 A/μs	-	379	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 5. Essentially independent of operating temperature typical characteristics.

#### **TYPICAL CHARACTERISTICS**

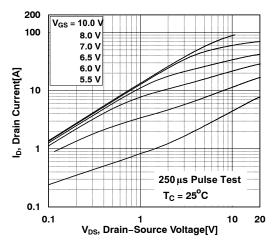


Figure 1. On–Region Characteristics

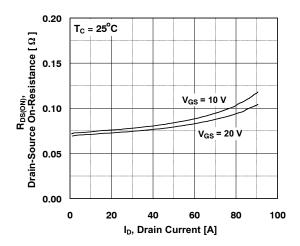
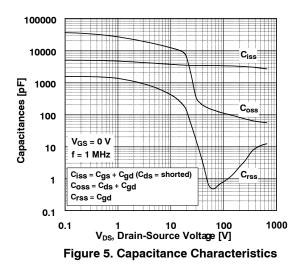


Figure 3. On–Resistance Variation vs. Drain Current and Gate Voltage



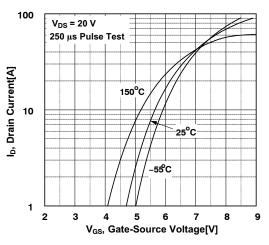


Figure 2. Transfer Characteristics

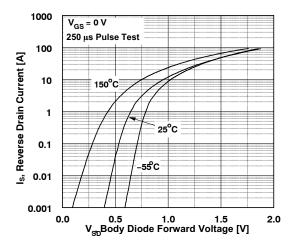


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

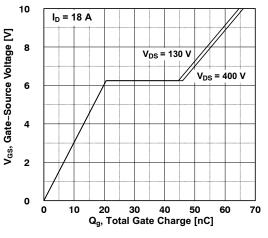
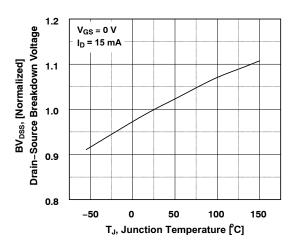
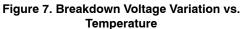


Figure 6. Gate Charge Characteristics

#### **TYPICAL CHARACTERISTICS**





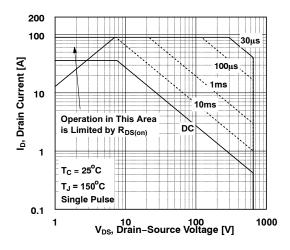


Figure 9. Maximum Safe Operating Area

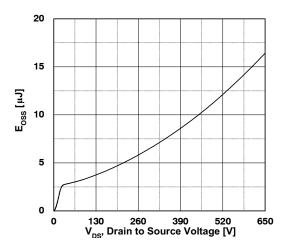


Figure 11. Eoss vs. Drain-to-Source Voltage

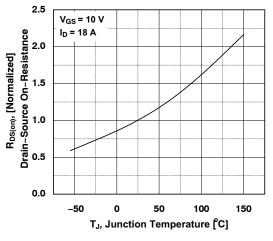


Figure 8. On–Resistance Variation vs. Temperature

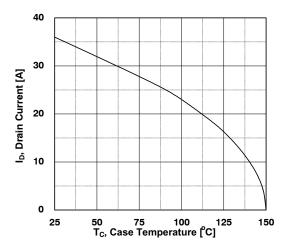


Figure 10. Maximum Drain Current vs. Case Temperature

#### **TYPICAL CHARACTERISTICS**

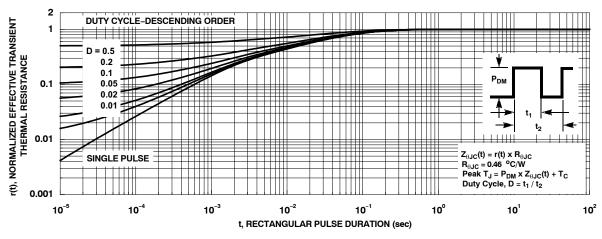


Figure 12. Transient Thermal Response Curve

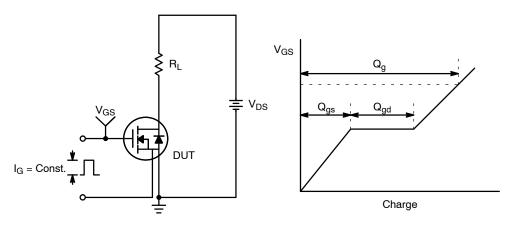


Figure 13. Gate Charge Test Circuit & Waveform

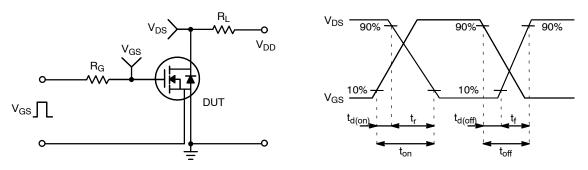
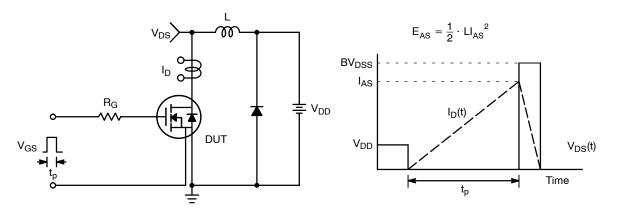


Figure 14. Resistive Switching Test Circuit & Waveforms





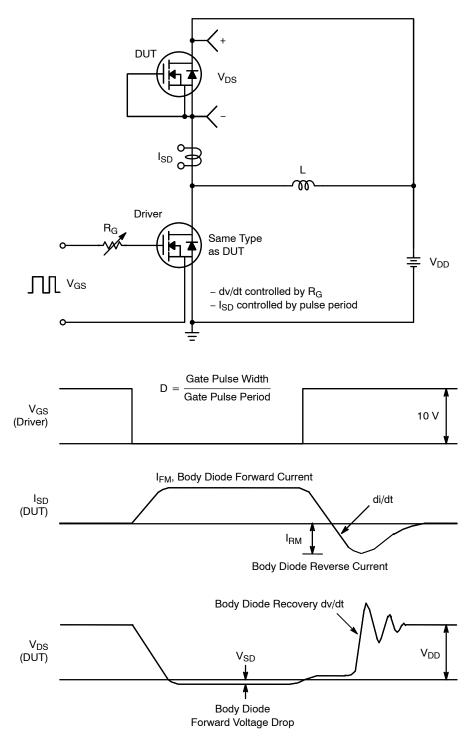
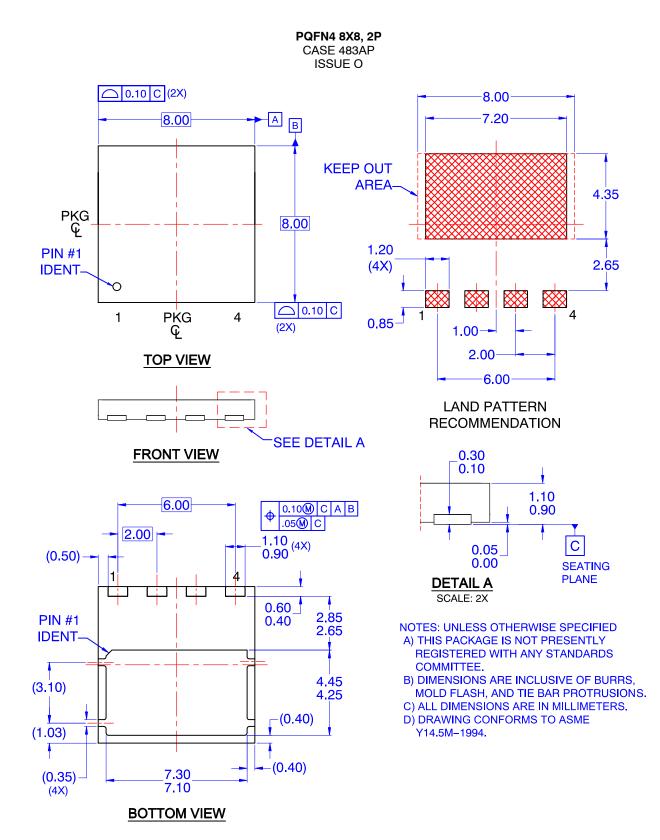


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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